

CLAIMS

(As Amended under PCT Article 34)

1. (Deleted)

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2. A method of cutting a lead terminal for a package type electronic component which comprises an element such as a semiconductor chip packaged in a molded part made of a synthetic resin with the lead terminal for said element projecting out of the molded part, the method comprising
10 the steps of:

indenting a main cutting notch on at least one of obverse and reverse surfaces of the lead terminal in a step before molding the molded part while leaving an
15 unnotched portion between the main notch and each longitudinal side surface of the lead terminal, then indenting a cutting sub-notch at the unnotched portion in a step after molding the molded part, and then cutting the lead terminal at the main notch and the sub-notch.

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3. (Amended) The lead terminal cutting method for a package type electronic component according to claim 1 or 2, wherein the lead terminal extends outwardly along a bottom surface of the molded part, the one surface of the
25 lead terminal on which the main notch or the combination of the main notch and the sub-notch is provided is

located on the side of the bottom surface of the molded part.

4. (Deleted)

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5. The lead terminal cutting method for a package type electronic component according to claim 2, further comprising a step of implementing a metal plating treatment with respect to the lead terminal at least 10 between the step of indenting the sub-notch and the step of cutting the lead terminal.

6. The lead terminal cutting method for a package type electronic component according to claim 2, further 15 comprising a step of implementing a first metal plating treatment with respect to the lead terminal at least between the step of indenting the main notch and the step of cutting the lead terminal, and a step of implementing a second metal plating treatment 20 with respect to the lead terminal at least between the step of indenting the sub-notch and the step of cutting the lead terminal.

7. (Amended) The lead terminal cutting method for a 25 package type electronic component according to claim 4 or 5, wherein the metal plating treatment includes plating

with nickel as an underlayer and plating with a metal having good solderability over the underlayer.

8. The lead terminal cutting method for a package type
5 electronic component according to claim 6, wherein the first metal plating treatment includes plating with nickel as an underlayer followed by plating with a metal having good solderability over the underlayer, and the second plating processing including plating with a metal
10 having solderability.